



Materials Declaration

Package	PDIP
Body Size	300 mils
LeadCount	24
Option	Pb Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	16	2.05 E-01	131320
SiO2 Filler	72	9.23 E-01	590940
Phenol Novolac	8	1.03 E-01	65660
Antimony_Sb2O3	2.2	2.82 E-02	18056
Brominated Resin	1.6	2.05 E-02	13132
Carbon Black	0.2	2.56 E-03	1641

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.33 E-01	149204
Fe	2.35	5.61 E-03	3596
P	0.03	7.17 E-05	46
Zn	0.12	2.87 E-04	184

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	1.11 E-03	708

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	2.65 E-02	16954

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	2.95 E-04	189

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	1.23 E-02	7879

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.92 E-04	123
Ag Filler	75	5.75 E-04	368

Molding Compound		
Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste		
Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals	
Weight (g)	PPM
1.56 E+00	1000000

AMK-N-G

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Fe	2.35	5.61 E-03	3596
P	0.03	7.17 E-05	46
Zn	0.12	2.87 E-04	184

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	1.11 E-03	708

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	2.25 E-02	14411
Pb	15	3.97 E-03	2543

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	2.95 E-04	189

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	1.23 E-02	7879

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
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